

Meeting Date: May 4, 2018

Meeting Location: Teleconference

### **VOTING MEMBERS AND 2018 PARTICIPANTS**

ANSYS Curtis Clark
Applied Simulation Technology (Fred Balistreri)
Broadcom (Yunong Gan)

Cadence Design Systems

Brad Brim\*, Ken Willis, Ambrish Varma
Cisco Systems

Stephen Scearce, Cassie Yan, Baosh Xu

CST Stefan Paret

Ericsson Anders Ekholm, Zilwan Mahmod, Guohua Wang

GLOBALFOUNDRIES Steve Parker\*
Huawei Technologies (Hang (Paul) Yan)
IBM Greg Edlund

Infineon Technologies AG (Christian Sporrer)

Intel Corporation Hsinho Wu\*, Michael Mirmak\*, Nilesh Dattani

Fernando Mendoza Hernandez, Varun Gupta

Subas Bastola, Hansel Dsilva

IO Methodology Lance Wang\*

Keysight Technologies Radek Biernacki\*, Ming Yan, Heidi Barnes

Pegah Alavi

Maxim Integrated Joe Engert, Yan Liang

Mentor, A Siemens Business Arpad Muranyi\*, Weston Beal, Raj Raghuram

Carlo Bleu, Mikael Stahlberg, Yasushi Kondou

Vladimir Dmitriev-Zdorov

Micron Technology Randy Wolff\*, Justin Butterfield

NXP (John Burnett)

Qualcomm Kevin Roselle, Tim Michalka

Raytheon Joseph Aday

SiSoft Mike LaBonte\*, Walter Katz\*, Todd Westerhoff

Synopsys Ted Mido, Adrien Auge\*, Scott Wedge

Teraspeed Labs

Xilinx

Ravindra Gali

ZTE Corporation

(Shunlin Zhu)

Zuken Michael Schaeder, Takayuki Shiratori

# **OTHER PARTICIPANTS IN 2018**

Google Zhiping Yang Haskware David Banas John Baprawski, Inc. John Baprawski KEI Systems Shinichi Maeda

Lattice Semiconductor Dinh Tran, Maryam Shahbazi

OmniVision Sirius Tsang Ricoh Kazuki Murata

RITA Electronics Ltd. Kenichi Higashiura, Hiroyuki Motoki

SAE-ITC (Jose Godoy)
Signal Metrics Ron Olisar
Socionext Megumi Ono
SPISim Wei-hsing Huang

Stanford University Tom Lee

Toshiba Yasuki Torigoshi, Yoshinori Fukuba

In the list above, attendees at the meeting are indicated by \*. Principal members or other active members who have not attended are in parentheses. Participants who no longer are in the organization are in square brackets.

## **UPCOMING MEETINGS**

The bridge numbers for future IBIS teleconferences are as follows:

Date Meeting Number Meeting Password

May 18, 2018 624 227 121 IBISfriday11

May 25, 2018 IBIS Summit at SPI – no teleconference

For teleconference dial-in information, use the password at the following website:

# http://tinyurl.com/y7yt7buz

All teleconference meetings are 8:00 a.m. to 9:55 a.m. US Pacific Time. Meeting agendas are typically distributed seven days before each Open Forum. Minutes are typically distributed within seven days of the corresponding meeting.

NOTE: "AR" = Action Required.

\_\_\_\_\_

## INTRODUCTIONS AND MEETING QUORUM

Mike LaBonte declared that a quorum was reached and the meeting could begin.

## **CALL FOR PATENTS**

Mike LaBonte called for declaration of any patents or pending patents related to the IBIS 3.2, IBIS 4.2, IBIS 5.1, IBIS 6.1, Touchstone 2.0, IBIS-ISS 1.0 or ICM 1.1 specifications. No patents were declared.

# **REVIEW OF MINUTES AND ARS**

Mike LaBonte called for comments on the minutes of the April 13, 2018 IBIS Open Forum teleconference. Bob Ross moved to approve the minutes. Michael Mirmak seconded the motion. There were no objections.

There were no ARs from the previous meeting to review.

# ANNOUNCEMENTS, CALL FOR ADDITIONAL AGENDA ITEMS

None.

# **MEMBERSHIP STATUS AND TREASURER'S REPORT**

Bob Ross reported that we have 26 members. There have been 18 renewals for 2018 so far. There is \$12,287 in the treasury. He is in contact with four companies intending to rejoin this month or later. If renewal payment is not received by May 31, an organization loses their vote. However, if renewal payment is received by June 15, a vote for officers will be counted in the officer election. About three companies have not responded to membership renewal requests. He noted that we also made the SPI Summit payment.

# **WEBSITE ADMINISTRATION**

Mike LaBonte reported that we have not had significant changes to our website. SAE-ITC has engaged more with us, and they are promoting the SPI Summit on their homepage on their top-level banner. They are also offering other promotions. It is possible we will have some new people clicking into our website. Mike has looked at our own website to see where we may want to make updates such as information about how to become a member.

### MAILING LIST ADMINISTRATION

Mike LaBonte reported that there have been typical changes. Some Freescale addresses had to be converted to NXP addresses.

# LIBRARY UPDATE

None.

# INTERNATIONAL/EXTERNAL ACTIVITIES

- Conferences

SPI2018 – the 22<sup>nd</sup> IEEE Workshop on Signal and Power Integrity will be held in Brest, France on May 22-25, 2018. An IBIS Summit will be held after the event. More information is available at:

https://spi2018.sciencesconf.org/

## - Press Update

Bob Ross reported on an online article from Eric Bogatin and others, "Validating IBIS Models with Measurements" in the Signal Integrity Journal. Bob noted the model used was based on a waveform extraction with 500 ohm loads, and this is not the recommended methodology. The measurement setup was based on PCB traces with impedances in the order of 50 ohms. Bob sent some comments to Eric Bogatin. He added that the Accuracy Handbook written by Greg Edlund does show some measurement methodology that is useful. Many vendors do measurement correlation with good results, better than that seen in the article. The article can be found at:

https://www.signalintegrityjournal.com/articles/799-validating-ibis-models-with-measurements

- Related standards IEC 63055/IEEE 2401, JEITA "LPB"

Michael Mirmak reported the first meeting of the IEEE 2401 specification team will take place Wednesday, May 16, 2018. There are IEEE participation rules involved. Mike LaBonte added that this meeting came up as a topic at the recent DASC meeting he and Michael attended. Michael commented that DASC made many positive references to IBIS in the meeting. Michael noted that any organization can attend an IEEE meeting once before needing to join as a member. This group is reconvening to consider changes to the LPB standard. Mike noted he will contact Tanaka-san to inquire about attending.

# **SUMMIT PLANNING AND STATUS**

- European IBIS Summit at SPI 2018

SPI 2018 will be held in Brest, France on May 22 through May 25, 2018. An IBIS Summit will be held the afternoon of Friday, May 25, 2018. One more announcement will go out today. The conference organizer has offered to conduct a short walking tour of historical sites after the Summit meeting. Mentor, a Siemens Business, SiSoft, Teraspeed Labs, and Zuken are sponsors.

Mike LaBonte noted some transit strikes in France that may create some travel difficulties. Walter Katz asked if someone will give a report on BIRD189. Walter noted Mike should make some remarks about BIRD189, since the SPI workshop relates to packaging. Mike responded he could expand his comments about upcoming changes to IBIS to include more detail of BIRD189. Bob Ross added he has penciled in 7 presentations so far.

## - EPEPS/EDI CON Discussion

Bob noted that EPEPS and EDI CON occur in the same week, so we cannot host a Summit at both events. We'll need to decide if we want to do a Summit in October at one of these events. Walter asked of the benefit to IBIS of attending one of these events. Bob noted it is extra work for officers to organize. On a personal level, it does help keep good relationships with the academic community with respect to EPEPS. With either event, it is an opportunity to increase visibility for IBIS.

Sponsorship opportunities for all upcoming IBIS summits are available, with sponsors receiving free mentions in the minutes, agenda, and other announcements. Contact the IBIS Board for further details.

#### **QUALITY TASK GROUP**

Mike LaBonte reported that the group is meeting on Tuesdays at 8:00 a.m. PT. The focus remains on IBISCHK related issues. Good progress is being made in preparing the developer contract with detailed information to help the developer and requirements for what an IBISCHK7 parser would do.

The IBISCHK6 user guide work in progress can be reviewed at:

http://www.ibis.org/ibischk6/ibischk\_6.1.4\_UserGuide\_wip1.pdf

The Quality task group checklist and other documentation can be found at:

http://www.ibis.org/quality\_wip/

#### ADVANCED TECHNOLOGY MODELING TASK GROUP

Arpad Muranyi reported that the group is meeting regularly on Tuesdays at 12:00 p.m. PT. The group finished a new BIRD draft of a clarification to BIRD158.7. It will be introduced today. The group is looking at their list of topics to address in upcoming meetings now that interconnect discussions have wrapped up.

Task group material can be found at:

http://www.ibis.org/macromodel\_wip/

## INTERCONNECT TASK GROUP

Michael Mirmak reported that the group is meeting at 8:00 a.m. PT on Wednesdays. The Friday Editorial task group time slot is also used on occasion. BIRD189.5 has been submitted. The group is working on a BIRD189.6 release with additional technical changes, but the discussion should close at the next meeting. Minor editorial work will be needed to wrap up BIRD189.

Task group material can be found at:

http://www.ibis.org/interconnect\_wip/

# **EDITORIAL TASK GROUP**

Michael Mirmak reported that this group remains suspended. Should there be any official document to review such as IBIS 7.0, the task group will resume meetings on Fridays when there is no Open Forum teleconference.

Since the last two remaining BIRDs for IBIS 7.0 are wrapping up, the Editorial task group will begin meeting soon. Some motions will be entertained soon regarding which BIRDs will be included in an IBIS 7.0 draft.

Task group material can be found at:

http://www.ibis.org/editorial\_wip/

#### **NEW ADMINISTRATIVE ISSUES**

None.

## BIRD189.5: INTERCONNECT MODELING USING IBIS-ISS AND TOUCHSTONE

Michael Mirmak reported on the major changes in the BIRD189.5 release. A number of changes have been made related to referencing and addressing concerns with BIRD194 interactions. The A\_gnd terminal was added. A BIRD189.6 is in progress, but the BIRD is close to being finalized. Bob Ross noted that he has not received comments on the draft BIRD189.6 yet. He requested feedback from the Interconnect task group. Mike noted markup in the draft is relative to the BIRD189.4 version.

#### BIRD194: REVISED AMI TS4FILE ANALOG BUFFER MODELS

Arpad Muranyi introduced the BIRD. This is a relatively simple BIRD with small changes. One of the biggest changes in BIRD189 is the addition of A\_gnd. Changes were made in BIRD194 relative to BIRD158.7 for A\_gnd. BIRD158.7 is already approved, so we decided to issue a new BIRD with the purpose of changing BIRD158.7. The entire text of BIRD158.7 is quoted. Mike LaBonte had an additional document with changes to BIRD158.7 highlighted in change tracking.

Arpad stated that the technical changes address how the original BIRD was not defining the triangle symbols showing the reference connection. The language mentioned a local ground, and this was replaced as a firm statement that the reference was A\_gnd as defined in the specification. This was done under the TX and RX schematics. A third drawing, that was a system level drawing showing interconnect between a TX and RX buffer, showed use of the global ground reference node. This drawing only showed one potential use of reference nodes. Discussion revealed that many iterations of this drawing would be necessary, and it was felt that the BIRD was mostly about the buffer models and not system information. The drawing and supporting text was removed.

Arpad noted that if this BIRD is approved, it will supersede BIRD158.7 in the specification. Bob Ross added that there were many voting options. If approved, we could put BIRD158.7 up for a re-vote with a recommendation to vote it down. Arpad didn't see a reason to re-vote on BIRD158.7. Randy Wolff suggested a motion indicate that BIRD194 would supersede BIRD158.7.

Walter Katz moved to schedule a vote at the next Open Forum meeting on BIRD194. Arpad Muranyi seconded the motion. There were no objections.

Radek Biernacki commented that we did not provide a warning statement in the BIRD about use of A\_gnd and potential referencing issues. We did need to move forward on the BIRD, but there are potential pitfalls between the interfacing of BIRD189 and BIRD194. Arpad commented that

we discussed writing cookbook type documentation to discuss these issues. Bob noted we took a warning out of the BIRD, but we still have the text in IBIS elsewhere. Radek added that for BIRD194, we have A\_gnd for both RX and TX, so there could be a bypass of referencing in the channel that could cause problems. Walter noted there is disagreement of people on generating power aware package models. He encouraged people to discuss this with others such as at SPI. The BIRD allows people to make models that work with multiple methods for power aware simulations, but model makers need to be careful.

## BIRD125.1: MAKE IBIS-ISS AVAILABLE FOR IBIS PACKAGE MODELING

Discussion was tabled.

# BIRD145.3: CASCADING IBIS I/O BUFFERS WITH [EXTERNAL CIRCUIT]S USING THE [MODEL CALL] KEYWORD

Discussion was tabled.

# BIRD163: INSTANTIATING AND CONNECTING [EXTERNAL CIRCUIT] PACKAGE MODELS WITH [CIRCUIT CALL]

Discussion was tabled.

# BIRD164: ALLOWING PACKAGE MODELS TO BE DEFINED IN [EXTERNAL CIRCUIT] Discussion was tabled.

# **BIRD166.4: RESOLVING PROBLEMS WITH REDRIVER INIT FLOW**

Discussion was tabled.

## **BIRD181.1: I-V TABLE CLARIFICATIONS**

Discussion was tabled.

# **BIRD190: CLARIFICATION FOR REDRIVER FLOW**

Discussion was tabled.

# **IBISCHK PARSER AND BUG STATUS**

Bob Ross reported there are no new bugs filed. He has a stack of possible bugs to be issued. The IBISCHK7 parser contract is being worked on.

# **NEW TECHNICAL ISSUES**

None.

#### **NEXT MEETING**

After some discussion of options, Arpad moved to hold the next IBIS Open Forum meeting on May 18, 2018. Walter Katz seconded the motion. There were no objections.

The IBIS Summit at SPI will be held on May 25, 2018. No teleconference will be available. The next IBIS Open Forum teleconference meeting will be held on May 18, 2018. A vote on BIRD194 is scheduled. The following IBIS Open Forum teleconference meeting is tentatively scheduled on June 8, 2018.

Walter moved to adjourn. Michael Mirmak seconded the motion. The meeting adjourned.

\_\_\_\_\_\_

## **NOTES**

IBIS CHAIR: Mike LaBonte

mlabonte@sisoft.com

IBIS-AMI Modeling Specialist, SiSoft 6 Clock Tower Place, Suite 250 Maynard, MA 01754

VICE CHAIR: Lance Wang (978) 633-3388

lwang@iometh.com

President/CEO, IO Methodology, Inc.

PO Box 2099 Acton, MA 01720

SECRETARY: Randy Wolff (208) 363-1764

rrwolff@micron.com

Principal Engineer, Silicon SI Group Lead, Micron Technology, Inc.

8000 S. Federal Way

P.O. Box 6, Mail Stop: 01-711

Boise, ID 83707-0006

TREASURER: Bob Ross (503) 246-8048

bob@teraspeedlabs.com

Engineer, Teraspeed Labs 10238 SW Lancaster Road

Portland, OR 97219

LIBRARIAN: Anders Ekholm (46) 10 714 27 58, Fax: (46) 8 757 23 40

ibis-librarian@ibis.org

Digital Modules Design, PDU Base Stations, Ericsson AB

BU Network Färögatan 6

164 80 Stockholm, Sweden

WEBMASTER: Mike LaBonte

mlabonte@sisoft.com

IBIS-AMI Modeling Specialist, SiSoft
6 Clock Tower Place, Suite 250

Maynard, MA 01754

POSTMASTER: Curtis Clark

curtis.clark@ansys.com

ANSYS, Inc.

150 Baker Ave Ext

Concord, MA 01742

This meeting was conducted in accordance with ANSI guidance.

All inquiries may be sent to <a href="mailto:info@ibis.org">info@ibis.org</a>. Examples of inquiries are:

- To obtain general information about IBIS.
- To ask specific questions for individual response.
- To subscribe to the official <a href="mailto:ibis@freelists.org">ibis@freelists.org</a> and/or <a href="mailto:ibis@eda.org">ibis-users@freelists.org</a> email lists (formerly ibis@eda.org and ibis-users@eda.org).
- To subscribe to one of the task group email lists: <a href="mailto:ibis-macro@freelists.org">ibis-macro@freelists.org</a>, <a href="mailto:ibis-macro@freelists.org">ibis-macro@freelists.org</a>, <a href="mailto:ibis-macro@freelists.org">ibis-macro@freelists.org</a>, <a href="mailto:ibis-macro@freelists.org">ibis-macro@freelists.org</a>, <a href="mailto:ibis-macro@freelists.org">ibis-macro@freelists.org</a>, <a href="mailto:ibis-macro@freelists.org">ibis-macro@freelists.org</a>, <a href="mailto:ibis-quality@freelists.org">ibis-quality@freelists.org</a>.
- To inquire about joining the IBIS Open Forum as a voting Member.
- To purchase a license for the IBIS parser source code.
- To report bugs or request enhancements to the free software tools: ibischk6, tschk2, icmchk1, s2ibis, s2ibis2 and s2iplt.

The BUG Report Form for ibischk resides along with reported BUGs at:

http://www.ibis.org/bugs/ibischk/ http://www.ibis.org/bugs/ibischk/bugform.txt

The BUG Report Form for tschk2 resides along with reported BUGs at:

http://www.ibis.org/bugs/tschk/http://www.ibis.org/bugs/tschk/bugform.txt

The BUG Report Form for icmchk resides along with reported BUGs at:

http://www.ibis.org/bugs/icmchk/ http://www.ibis.org/bugs/icmchk/icm\_bugform.txt

To report s2ibis, s2ibis2 and s2ipIt bugs, use the Bug Report Forms which reside at:

http://www.ibis.org/bugs/s2ibis/bugs2i.txt http://www.ibis.org/bugs/s2ibis2/bugs2i2.txt http://www.ibis.org/bugs/s2iplt/bugsplt.txt Information on IBIS technical contents, IBIS participants and actual IBIS models are available on the IBIS Home page:

http://www.ibis.org/

Check the IBIS file directory on ibis.org for more information on previous discussions and results:

http://www.ibis.org/directory.html

Other trademarks, brands and names are the property of their respective owners.

# SAE STANDARDS BALLOT VOTING STATUS

		Standards Ballot				
Organization	Interest Category	Voting Status	March 9, 2018	March 23, 2018	April 13, 2018	May 4, 2018
ANSYS	User	Active	Х	X	Х	-
Applied Simulation Technology	User	Inactive	-	-	-	-
Broadcom Ltd.	Producer	Inactive	-	-	-	-
Cadence Design Systems	User	Active	-	Χ	X	X
Cisco Systems	User	Inactive	-	-	-	-
CST	User	Inactive	-	-	-	-
Ericsson	Producer	Inactive	-	-	-	-
GLOBALFOUNDRIES	Producer	Active	X	-	X	Χ
Huawei Technologies	Producer	Inactive	-	-	-	-
IBM	Producer	Inactive	-	-	-	-
Infineon Technologies AG	Producer	Inactive	-	-	-	-
Intel Corp.	Producer	Active	X	Χ	X	Χ
IO Methodology	User	Active	-	X	X	Χ
Keysight Technologies	User	Active	X	X	Χ	X
Maxim Integrated	Producer	Inactive	-	-	-	-
Mentor, A Siemens Business	User	Active	X	X	X	Χ
Micron Technology	Producer	Active	X	X	Χ	X
NXP	Producer	Inactive	-	-	-	-
Qualcomm	Producer	Inactive	-	-	-	-
Raytheon	User	Inactive	-	=	-	-
SiSoft	User	Active	X	X	X	Χ
Synopsys	User	Active	X	X	-	X
Teraspeed Labs	General Interest	Active	X	X	X	X
Xilinx	Producer	Inactive	-	-	-	-
ZTE Corp.	User	Inactive	-	-	-	-
Zuken	User	Inactive	-	-	-	-

Criteria for SAE member in good standing:

- Must attend two consecutive meetings to establish voting membership
- Membership dues current
- Must not miss two consecutive meetings

Interest categories associated with SAE standards ballot voting are:

- Users members that utilize electronic equipment to provide services to an end user.
- Producers members that supply electronic equipment.
- General Interest members are neither producers nor users. This category includes, but is not limited to, government, regulatory agencies (state and federal), researchers, other organizations and associations, and/or consumers.